

Application Data Sheet

Application Information

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| Application Type:: | Regular |
| Subject Matter:: | Utility |
| Suggested classification:: | |
| Suggested Group Art Unit:: | |
| CD-ROM or CD-R?:: | None |
| Computer Readable Form (CRF)?:: | No |
| Title:: | WAFER HEAT-TREATMENT SYSTEM AND WAFER HEAT-TREATMENT METHOD |
| Attorney Docket Number:: | 025311-0115 |
| Request for Early Publication?:: | No |
| Request for Non-Publication?:: | No |
| Suggested Drawing Figure:: | 1 |
| Total Drawing Sheets:: | 3 |
| Small Entity?:: | No |
| Petition included?:: | No |
| Secrecy Order in Parent Appl.?:: | No |

Applicant Information

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|--------------------------------------|---------------|
| Applicant Authority Type:: | Inventor |
| Primary Citizenship Country:: | Japanese |
| Status:: | Full Capacity |
| Given Name:: | Yoshimasa |
| Family Name:: | KAWASE |
| City of Residence:: | Kanagawa |
| Country of Residence:: | Japan |

Street of mailing address:: c/o Semiconductor Leading Edge Technologies, Inc.
292 Yoshida-cho, Totsuka-ku, Yokohama
Kanagawa 244-0817, Japan

Country of mailing address:: Japan

Correspondence Information

Correspondence Customer Number:: 22428

E-Mail address:: wellis@foleylaw.com

Representative Information

| | | |
|---|-------|--|
| Representative Customer Number:: | 22428 | |
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Domestic Priority Information

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|----------------------|--------------------------|-----------------------------|-----------------------------|
| Application:: | Continuity Type:: | Parent Application:: | Parent Filing Date:: |
| | | | |

Foreign Priority Information

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|------------------|-----------------------------|----------------------|---------------------------|
| Country:: | Application number:: | Filing Date:: | Priority Claimed:: |
| Japan | 2001-036040 | 02/13/2001 | Yes |

Assignee Information

Assignee name:: SEMICONDUCTOR LEADING EDGE
TECHNOLOGIES, INC.